



## **Infineon Technologies Packaging Center Regensburg-Burgweinting Key Facts**

Lead fab for technology, innovation and marketing

Development and volume production of modules for chip card applications

Since 1990: assembly of chip card modules in Regensburg

August 2000: new production site in Regensburg-Burgweinting

|                            |  |
|----------------------------|--|
| Total area:                | 2,500 m <sup>2</sup>   |
| Production volume:         | 670 million modules in FY 2003/04 (in total 3 billion modules by July 2004)  |
| Employees:                 | 260 (total employees at site Regensburg: approx. 2,800)  |
| Products and Technologies: | chip card modules in wirebond and FCOS™ technology,<br>contactless modules in mold and flip chip technology,<br>RFID inlays<br>Pre-assembly: wafer thinning, dicing, bumping |

The packaging center Regensburg-Burgweinting, together with its Chinese plant in Wuxi, is worldwide market leader for chip card modules.